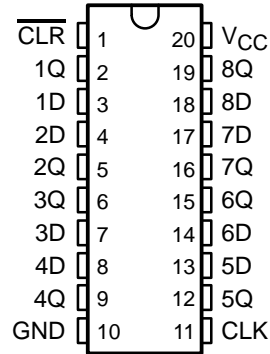


SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

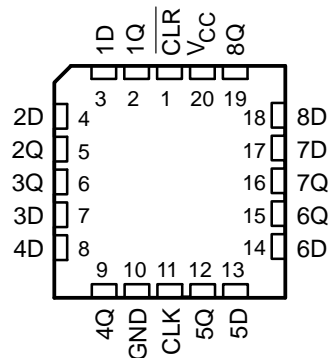
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- Inputs Are TTL-Voltage Compatible
- Contain Eight Flip-Flops With Single-Rail Outputs
- Direct Clear Input
- Individual Data Input to Each Flip-Flop
- Applications Include:
 - Buffer/Storage Registers
 - Shift Registers
 - Pattern Generators
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)

SN54AHCT273 . . . J OR W PACKAGE
SN74AHCT273 . . . DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)



SN54AHCT273 . . . FK PACKAGE
(TOP VIEW)



description

These devices are positive-edge-triggered D-type flip-flops with a direct clear (CLR) input.

Information at the data (D) inputs meeting the setup time requirements is transferred to the Q outputs on the positive-going edge of the clock (CLK) pulse. Clock triggering occurs at a particular voltage level and is not directly related to the transition time of the positive-going pulse. When CLK is at either the high or low level, the D input has no effect at the output.

ORDERING INFORMATION

| T _A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|---------------|-----------------|-----------------------|------------------|
| –40°C to 85°C | PDIP – N | Tube | SN74AHCT273N | SN74AHCT273N |
| | SOIC – DW | Tube | SN74AHCT273DW | AHCT273 |
| | | Tape and reel | SN74AHCT273DWR | |
| | SOP – NS | Tape and reel | SN74AHCT273NSR | AHCT273 |
| | SSOP – DB | Tape and reel | SN74AHCT273DBR | HB273 |
| | TSSOP – PW | Tape and reel | SN74AHCT273PWR | HB273 |
| TVSOP – DGV | Tape and reel | SN74AHCT273DGVR | HB273 | |
| –55°C to 125°C | CDIP – J | Tube | SNJ54AHCT273J | SNJ54AHCT273J |
| | CFP – W | Tube | SNJ54AHCT273W | SNJ54AHCT273W |
| | LCCC – FK | Tube | SNJ54AHCT273FK | SNJ54AHCT273FK |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

UNLESS OTHERWISE NOTED this document contains PRODUCTION DATA information current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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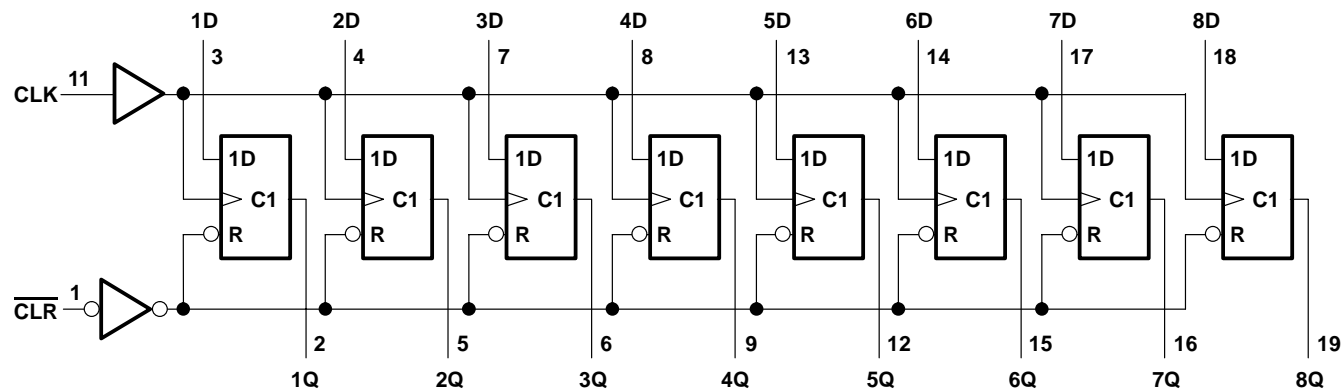
SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

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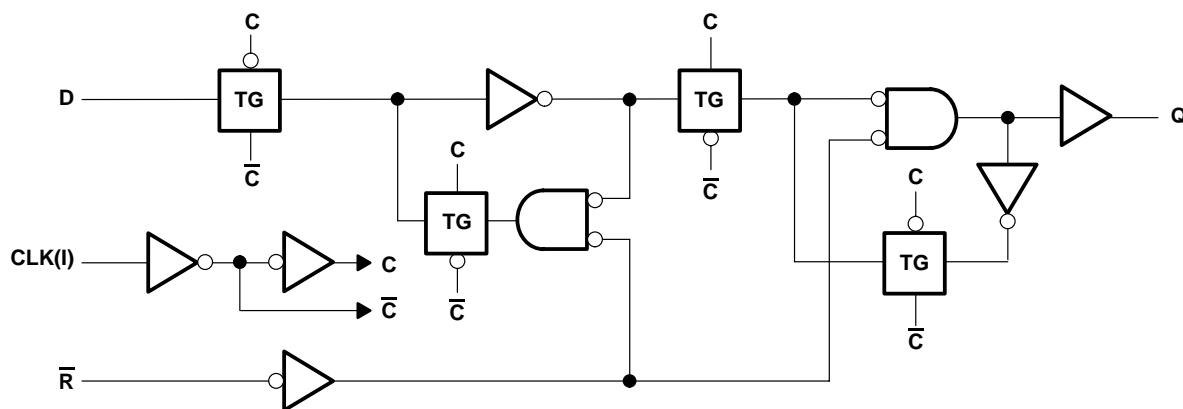
FUNCTION TABLE
(each flip-flop)

| INPUTS | | | OUTPUT |
|-------------------------|------------|---|--------|
| $\overline{\text{CLR}}$ | CLK | D | Q |
| L | X | X | L |
| H | \uparrow | H | H |
| H | \uparrow | L | L |
| H | L | X | Q_0 |

logic diagram (positive logic)



logic diagram, each flip-flop (positive logic)



SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|--|----------------------------|
| Supply voltage range, V_{CC} | –0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | –0.5 V to 7 V |
| Output voltage range, V_O (see Note 1) | –0.5 V to $V_{CC} + 0.5$ V |
| Input clamp current, I_{IK} ($V_I < 0$) | –20 mA |
| Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$) | ±20 mA |
| Continuous output current, I_O ($V_O = 0$ to V_{CC}) | ±25 mA |
| Continuous current through V_{CC} or GND | ±75 mA |
| Package thermal impedance, θ_{JA} (see Note 2): | |
| DB package | 70°C/W |
| DGV package | 92°C/W |
| DW package | 58°C/W |
| N package | 69°C/W |
| NS package | 60°C/W |
| PW package | 83°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

| | SN54AHCT273 | | SN74AHCT273 | | UNIT |
|--|-------------|----------|-------------|----------|------|
| | MIN | MAX | MIN | MAX | |
| V_{CC} Supply voltage | 4.5 | 5.5 | 4.5 | 5.5 | V |
| V_{IH} High-level input voltage | 2 | | 2 | | V |
| V_{IL} Low-level input voltage | | 0.8 | | 0.8 | V |
| V_I Input voltage | 0 | 5.5 | 0 | 5.5 | V |
| V_O Output voltage | 0 | V_{CC} | 0 | V_{CC} | V |
| I_{OH} High-level output current | | –8 | | –8 | mA |
| I_{OL} Low-level output current | | 8 | | 8 | mA |
| $\Delta t/\Delta v$ Input transition rise or fall time | | 20 | | 20 | ns/V |
| T_A Operating free-air temperature | –55 | 125 | –40 | 85 | °C |

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | V _{CC} | T _A = 25°C | | | SN54AHCT273 | | SN74AHCT273 | | UNIT |
|--------------------|---|-----------------|-----------------------|-----|------|-------------|------|-------------|-----|------|
| | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| V _{OH} | I _{OH} = -50 μA | 4.5 V | 4.4 | 4.5 | | 4.4 | | 4.4 | V | |
| | I _{OH} = -8 mA | | 3.94 | | | 3.8 | | 3.8 | | |
| V _{OL} | I _{OL} = 50 μA | 4.5 V | | | 0.1 | | | 0.1 | V | |
| | I _{OL} = 8 mA | | | | 0.36 | | 0.44 | 0.44 | | |
| I _I | V _I = 5.5 V or GND | 0 V to 5.5 V | | | ±0.1 | | | ±1 | μA | |
| I _{CC} | V _I = V _{CC} or GND, I _O = 0 | 5.5 V | | | 4 | | 40 | 40 | μA | |
| ΔI _{CC} † | One input at 3.4 V, Other inputs at V _{CC} or GND | 5.5 V | | | 1.35 | | 1.5 | 1.5 | mA | |
| C _i | V _I = V _{CC} or GND | 5 V | | 2.5 | 10 | | | 10 | pF | |

* On products compliant to MIL-PRF-38535, this parameter is not production tested at V_{CC} = 0 V.

† This is the increase in supply current for each input at one of the specified TTL voltage levels rather than 0 V or V_{CC}.

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

| | | T _A = 25°C | | SN54AHCT273 | | SN74AHCT273 | | UNIT |
|-----------------|----------------------------|-----------------------|-----|-------------|-----|-------------|-----|------|
| | | MIN | MAX | MIN | MAX | MIN | MAX | |
| t _w | Pulse duration | CLR low | 5 | | 6 | | 6 | ns |
| | | CLK high or low | 5 | | 6.5 | | 6.5 | |
| t _{su} | Setup time | Data before CLK↑ | 5 | | 5 | | 5 | ns |
| | | CLR before CLK↑ | 2.5 | | 2.5 | | 2.5 | |
| t _h | Hold time, data after CLK↑ | | 0 | | 0 | | 0 | ns |

switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | LOAD CAPACITANCE | T _A = 25°C | | | SN54AHCT273 | | SN74AHCT273 | | UNIT |
|--------------------|--------------|-------------|------------------------|-----------------------|-------|-------|-------------|--------|-------------|------|------|
| | | | | MIN | TYP | MAX | MIN | MAX | MIN | MAX | |
| f _{max} | | | C _L = 15 pF | 75** | 120** | | 65** | | 65 | MHz | |
| | | | C _L = 50 pF | 50 | 75 | | 45 | | 45 | | |
| t _{PHL} | CLR | Q | C _L = 15 pF | | 7.5** | 10** | 1** | 11.6** | 1 | 11.6 | ns |
| t _{PLH} | CLK | Q | C _L = 15 pF | | 5.5** | 7.5** | 1** | 8.8** | 1 | 8.8 | ns |
| t _{PHL} | | | | | 5.8** | 8.2** | 1** | 10** | 1 | 10 | |
| t _{PHL} | CLR | Q | C _L = 50 pF | | 8.5 | 11 | 1 | 12.6 | 1 | 12.6 | ns |
| t _{PLH} | CLK | Q | C _L = 50 pF | | 6.5 | 8.5 | 1 | 9.8 | 1 | 9.8 | ns |
| t _{PHL} | | | | | 6.8 | 9.2 | 1 | 11 | 1 | 11 | |
| t _{sk(o)} | | | C _L = 50 pF | | | 1*** | | | 1 | ns | |

** On products compliant to MIL-PRF-38535, this parameter is not production tested.

*** On products compliant to MIL-PRF-38535, this parameter does not apply.

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



SN54AHCT273, SN74AHCT273
OCTAL D-TYPE FLIP-FLOPS
WITH CLEAR

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noise characteristics, $V_{CC} = 5\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Note 4)

| PARAMETER | SN74AHCT273 | | | UNIT |
|--|-------------|-------|-----|------|
| | MIN | TYP | MAX | |
| $V_{OL(P)}$ Quiet output, maximum dynamic V_{OL} | | 0.76 | | V |
| $V_{OL(V)}$ Quiet output, minimum dynamic V_{OL} | | -0.48 | | V |
| $V_{OH(V)}$ Quiet output, minimum dynamic V_{OH} | | 4.4 | | V |
| $V_{IH(D)}$ High-level dynamic input voltage | | 2 | | V |
| $V_{IL(D)}$ Low-level dynamic input voltage | | | 0.8 | V |

NOTE 4: Characteristics are for surface-mount packages only.

operating characteristics, $T_A = 25^\circ\text{C}$

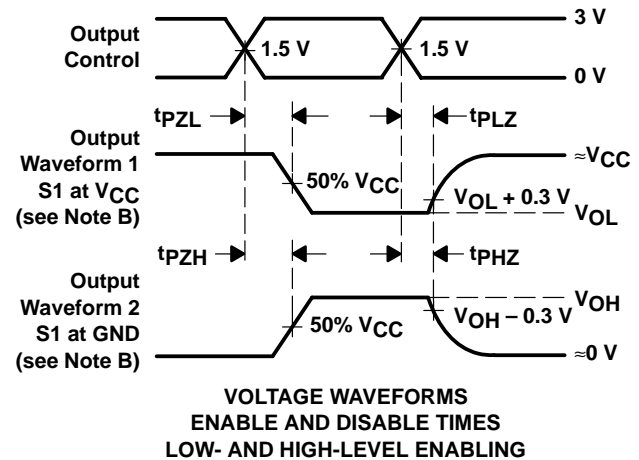
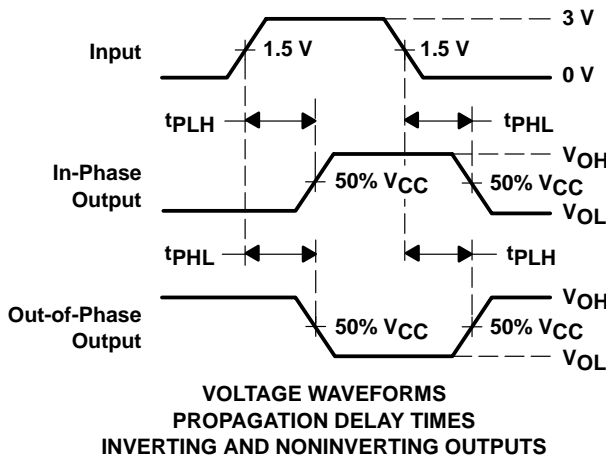
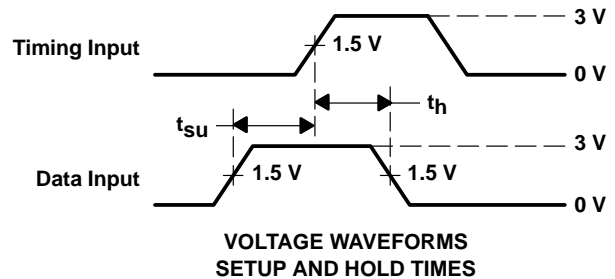
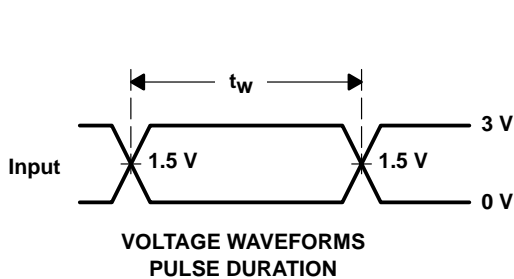
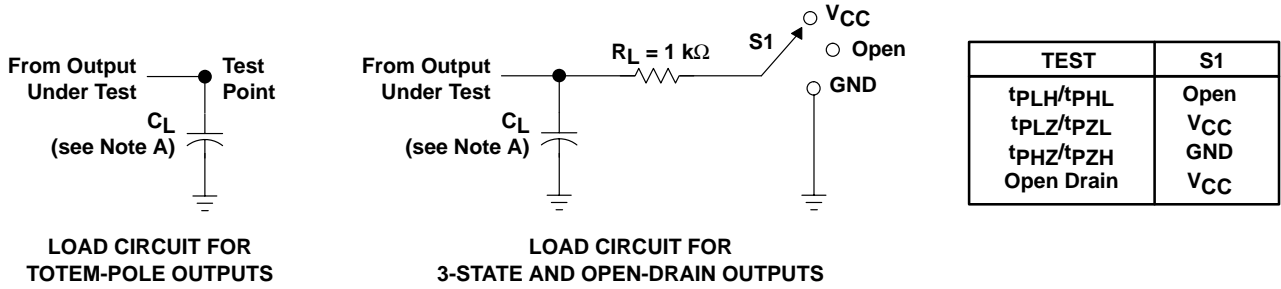
| PARAMETER | TEST CONDITIONS | TYP | UNIT |
|--|-----------------------------|-----|------|
| C_{pd} Power dissipation capacitance | No load, $f = 1\text{ MHz}$ | 27 | pF |



SN54AHCT273, SN74AHCT273 OCTAL D-TYPE FLIP-FLOPS WITH CLEAR

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PARAMETER MEASUREMENT INFORMATION






- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|-------------------|---------------|--------------|--------------------|------|-------------|----------------------------|------------------|----------------------|--------------|--------------------------|-------------------------|
| SN74AHCT273DBR | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 | Samples |
| SN74AHCT273DBRE4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 | Samples |
| SN74AHCT273DBRG4 | ACTIVE | SSOP | DB | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 | Samples |
| SN74AHCT273DGV | ACTIVE | TVSOP | DGV | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 | Samples |
| SN74AHCT273DGVRE4 | ACTIVE | TVSOP | DGV | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 | Samples |
| SN74AHCT273DVG4 | ACTIVE | TVSOP | DGV | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 | Samples |
| SN74AHCT273DW | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273DWE4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273DWG4 | ACTIVE | SOIC | DW | 20 | 25 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273DWR | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273DWRE4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273DWRG4 | ACTIVE | SOIC | DW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273N | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74AHCT273N | Samples |
| SN74AHCT273NE4 | ACTIVE | PDIP | N | 20 | 20 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -40 to 85 | SN74AHCT273N | Samples |
| SN74AHCT273NSR | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273NSRE4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |
| SN74AHCT273NSRG4 | ACTIVE | SO | NS | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | AHCT273 | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish | MSL Peak Temp (3) | Op Temp (°C) | Top-Side Markings (4) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|------------------|----------------------|--------------|--------------------------|---|
| SN74AHCT273PWR | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 |  |
| SN74AHCT273PWRE4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 |  |
| SN74AHCT273PWRG4 | ACTIVE | TSSOP | PW | 20 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -40 to 85 | HB273 |  |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74AHCT273DBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74AHCT273DGVR | TVSOP | DGV | 20 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74AHCT273DWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.0 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74AHCT273NSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.2 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |
| SN74AHCT273PWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74AHCT273DBR | SSOP | DB | 20 | 2000 | 367.0 | 367.0 | 38.0 |
| SN74AHCT273DGVR | TVSOP | DGV | 20 | 2000 | 367.0 | 367.0 | 35.0 |
| SN74AHCT273DWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74AHCT273NSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74AHCT273PWR | TSSOP | PW | 20 | 2000 | 367.0 | 367.0 | 38.0 |

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - D The 20 pin end lead shoulder width is a vendor option, either half or full width.

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DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

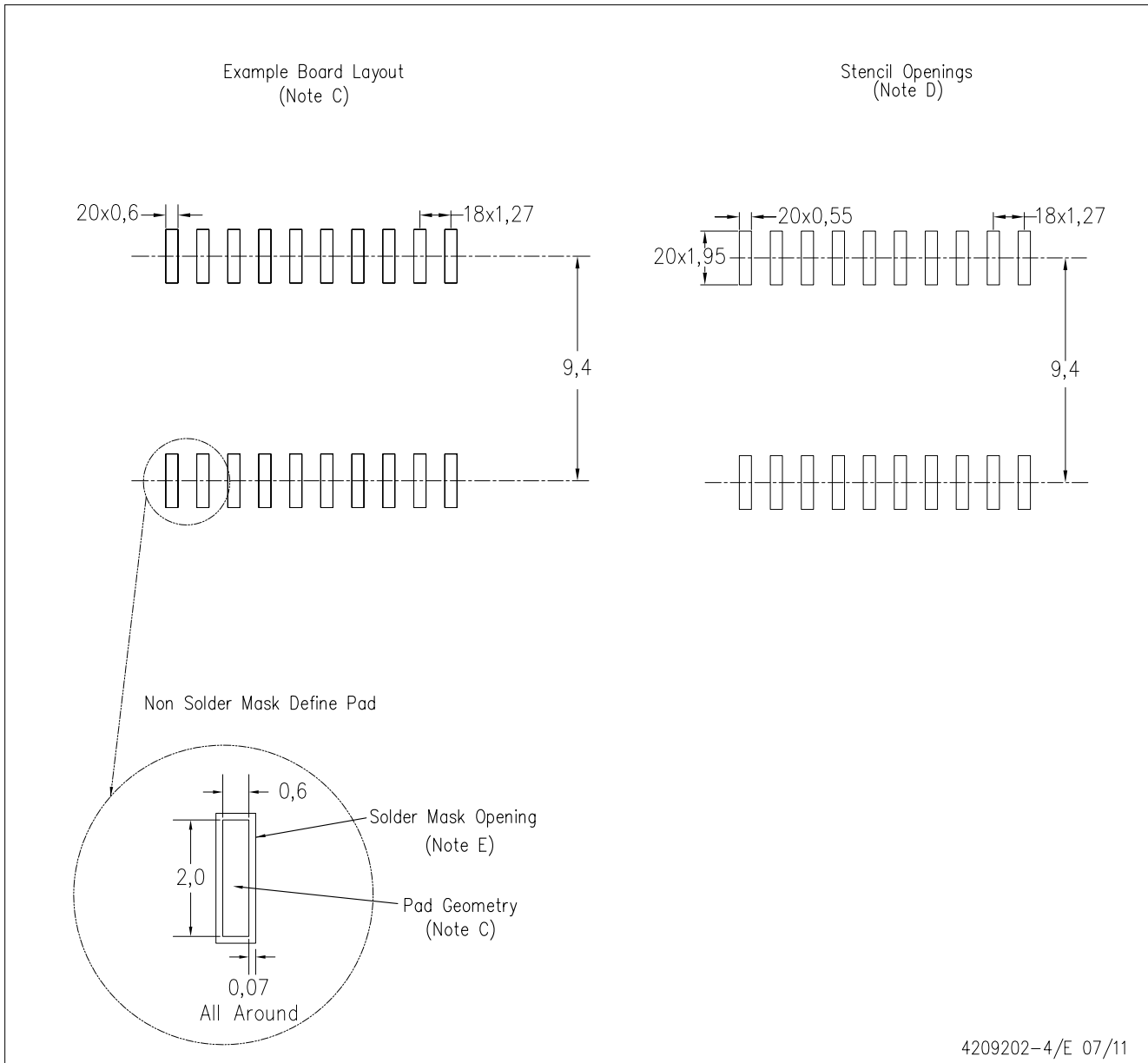


4073251/E 08/00

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



4209202-4/E 07/11

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G20)

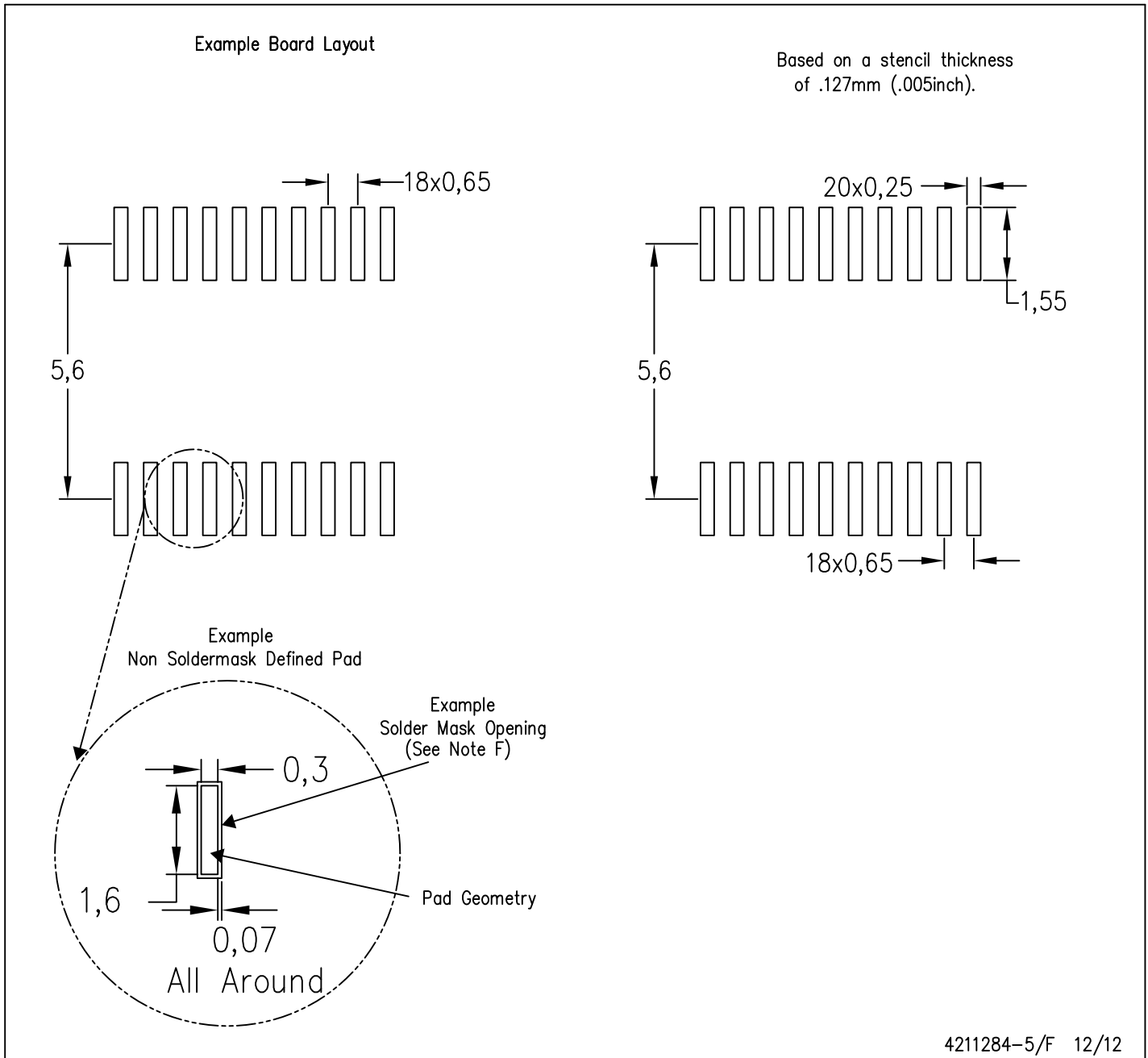
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

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